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RE: Application 09/133,989

12. (Three times amended) A processor for a spin coating device including a chuck defining a wafer accommodation area, comprising:

at least one dispenser of a first material that is a solvent with respect to a second material on a wafer configured to occupy said wafer accommodation area; and

a suction mechanism [generally around] surrounding said at least one solvent dispenser and offset from said wafer accommodation area during an operational mode of said device.

13. The processor in claim 12, wherein said at least one dispenser further comprises:

a first dispenser on a first side of said wafer accommodation area; and

a second dispenser on a second side of said wafer accommodation area.

14. (Three times amended) A bead remover for a wafer, comprising:

a negative pressure mechanism configured to be spaced from a bead on said wafer while operating upon said bead; and

a dispensing mechanism aligned within said negative pressure mechanism, wherein said dispensing mechanism is configured to deliver a chemical that dissolves said bead.

15. (Twice amended) A bead remover for a wafer, comprising:

a negative pressure mechanism configured to be spaced from a bead on said wafer while operating upon said bead; and

a solvent-dispensing mechanism aligned with said negative pressure mechanism, wherein said solvent-dispensing mechanism is concentric to said negative pressure mechanism, and wherein said solvent-dispensing mechanism is configured to be located above said bead while operating on said bead.

16. (Once amended) [The bead remover of claim 15] A bead remover for a wafer, comprising:

a negative pressure mechanism configured to be spaced from a bead on said wafer while operating upon said bead; and

a solvent-dispensing mechanism aligned with said negative pressure mechanism, wherein said solvent-dispensing mechanism is concentric to said negative pressure mechanism, wherein said solvent-dispensing mechanism is [generally] within said negative pressure mechanism.

17. An edge bead remover configured to service a spinning wafer, comprising:

a nozzle configured to apply an edge bead-dissolving substance to an edge of said wafer; and

a vacuum mechanism *enveloping said nozzle* and offset from an edge bead during application of said substance to said edge.

18. The edge bead remover of claim 17, wherein said vacuum mechanism is configured to remove said substance from said edge.

19. An edge bead remover configured to service a spinning wafer, comprising:

a nozzle configured to apply an edge bead-dissolving substance to an edge of said wafer; and

a vacuum mechanism *enveloping said nozzle* and offset from said edge during application of said substance to said edge, wherein said vacuum mechanism is configured to remove said substance from said edge, and wherein said vacuum mechanism envelopes said edge.

20. (Three times amended) A material removal system for a wafer, comprising:

a negative pressure device defining a vacuum area intersecting said wafer while said device is in an operational position; and

a solvent dispenser [intersecting] inside of said vacuum area and aligned with an edge of said wafer while said device is in said operational position.

21. The material removal system of claim 20, wherein said negative pressure device is distal from said wafer while said device is in said operational position.

22. An edge bead removal system for a wafer having an edge and a top and a bottom, comprising:

a first solvent nozzle poised above said top of said wafer at said edge during a dispensing mode of said system;

a second solvent nozzle poised below said bottom of said wafer at said edge during said dispensing mode; and

a suction device *encompassing said first solvent nozzle* and said second solvent nozzle.

23. The edge bead removal system in claim 22, wherein said suction device encompasses said top and said bottom of said wafer at said edge.

24. A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from all surfaces of said workpiece while acting upon said workpiece; and

a first dispenser *within said negative pressure device* and disposed toward at least one surface of said workpiece while dispensing a chemical that dissolves a material on said workpiece.

25. The chemical dispensing system in claim 24, wherein said portal is spaced around an edge of said workpiece.

26. A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from all surfaces of said workpiece while acting upon said workpiece, wherein said portal is spaced around an edge of said workpiece;

a first solvent dispenser *within said negative pressure device* and disposed toward at least one surface of said workpiece while acting upon said workpiece; and

a second solvent dispenser within said negative pressure device, disposed toward said edge, and opposing said first solvent dispenser.

27. The chemical dispensing system in claim 26, wherein said first solvent dispenser and said second solvent dispenser are within said portal.

28. (Three times amended) A chemical remover for a substrate, comprising:

a nozzle directed toward said substrate during a dispensation mode, above said substrate during said dispensation mode, and configured to couple to a source of a chemical that can dissolve a material on said substrate; and

a vacuum device spaced from said material and directed toward said nozzle during said dispensation mode.

29. (Three times amended) A profiler for a wafer, comprising:

a dispenser perpendicular to said wafer during a dissolution process; and

a vacuumer surrounding [at least a portion of] said dispenser and separate from an outermost surface of said wafer during said dissolution process.

30. The profiler in claim 29, wherein said dispenser further comprises a location wherein solvent exits said dispenser; and wherein said vacuumer surrounds said location.

31. (Three times amended) A profiler for a wafer, comprising:

a dispenser perpendicular to said wafer during a dissolution process and comprising a location wherein solvent exits said dispenser;

a vacuumer surrounding [at least a portion of] said dispenser and separate from said wafer during said dissolution process, wherein said vacuumer surrounds said location; and

an additional dispenser perpendicular to said wafer; wherein said vacuumer surrounds at least a portion of said additional dispenser.

32. (Three times amended) [The profiler in claim 31] A profiler for a wafer, comprising:

a dispenser perpendicular to said wafer during a dissolution process and comprising a location wherein solvent exits said dispenser, wherein said dispenser is disposed toward a top side of said wafer;

a vacuumer surrounding at least a portion of said dispenser and separate from said wafer during said dissolution process, wherein said vacuumer surrounds said location; and

an additional dispenser perpendicular to said wafer; wherein said vacuumer surrounds at least a portion of said additional dispenser.

33. The profiler in claim 32, wherein said additional dispenser is disposed toward a bottom side of said wafer.